

What is claimed is:

1. A method for removing a die from a plastic package, comprising:
removing a package cap from a top surface of the plastic package;
heating the plastic package enough such that the plastic package cracks, the cracking
resulting in at least one fracture in the plastic package; and
grasping the plastic package on either side of the fracture and opening the package to
detach the die from the cracked plastic package.
2. The method of claim 1, wherein the plastic package is held by two pairs of pliers, one
pair of pliers on either side of the fracture.
3. The method of claim 2, wherein the two pairs of pliers are pulled in two opposite
directions that are substantially a same plane.
4. The method of claim 2, wherein the two pairs of pliers are pulled in two opposite
directions in two planes that are parallel to each other.
5. The method of claim 2, wherein one of the two pairs of pliers is twisted in a clockwise
direction and the other of the two pairs of pliers is twisted in a counter-clockwise direction.
6. The method of claim 2, wherein each pair of pliers grasps one area of the plastic
package on one side of the fracture and the two areas that are grasped by the two pairs of
pliers are substantially away from the die.
7. The method of claim 6, wherein each of the two pairs of pliers has a pair of flat
surfaces and each pair of pliers grasps one of the two areas using its pair of flat surfaces.
8. The method of claim 1, wherein the die is attached to the plastic package through an
array of solder connections and epoxy material.
9. The method of claim 8, wherein the plastic package is heated sufficiently high to melt
down the solder connections and the epoxy material without damaging the die.
10. The method of claim 1, wherein the step of heating the plastic package comprises
placing the plastic package on a hot plate.
11. The method of claim 10, wherein the temperature of the hot plate is about 460°C.